

**TGD N-Channel Super Trench Power MOSFET****Description**

The TGDP0178AL uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

General Features

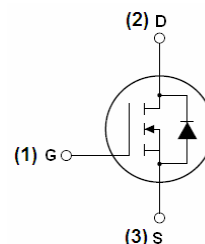
- $V_{DS} = 100V, I_D = 78A$
 $R_{DS(ON)} = 7.2m\Omega$ (typical) @ $V_{GS} = 10V$
 $R_{DS(ON)} = 9.5m\Omega$ (typical) @ $V_{GS} = 4.5V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)
- Very low on-resistance $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating
- 100% UIS tested

Application

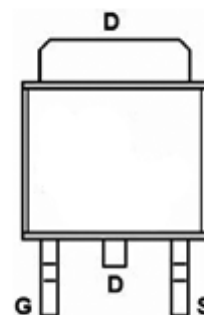
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

100% UIS TESTED!

100% ΔV_{ds} TESTED!



Schematic diagram



pin assignment



TO-251S top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
TGDP0178AL	TGDP0178AL	TO-251S	-	-	-

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	78	A
Drain Current-Continuous($T_C = 100^\circ\text{C}$)	$I_D (100^\circ\text{C})$	60	A
Pulsed Drain Current	I_{DM}	320	A
Maximum Power Dissipation	P_D	125	W
Derating factor		0.83	W/ $^\circ\text{C}$
Single pulse avalanche energy ^(Note 5)	E_{AS}	320	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ\text{C}$



Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	1.2	$^{\circ}\text{C/W}$
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Electrical Characteristics ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

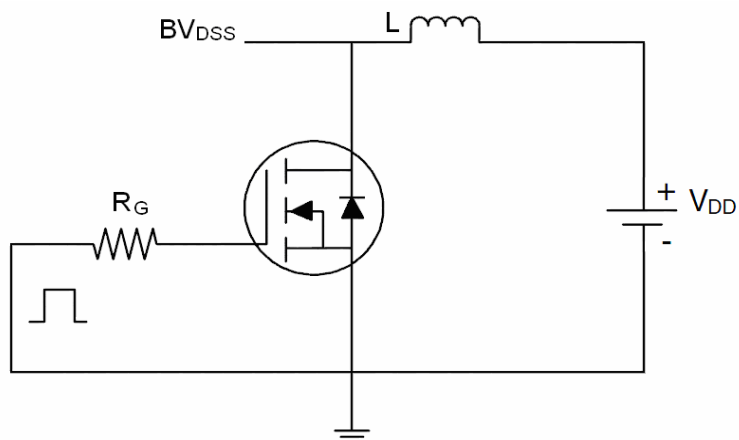
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	100		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.2	1.7	2.2	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =39A	-	7.2	8.5	mΩ
		V _{GS} =4.5V, I _D =39A	-	9.5	12	mΩ
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =39A	40	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{ISS}	V _{DS} =50V, V _{GS} =0V, F=1.0MHz	-	4200	5480	PF
Output Capacitance	C _{OSS}		-	354	425	PF
Reverse Transfer Capacitance	C _{RSS}		-	23	30	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V _{DD} =50V, I _D =39A V _{GS} =10V, R _G =4.7Ω	-	15	-	nS
Turn-on Rise Time	t _r		-	10	-	nS
Turn-Off Delay Time	t _{d(off)}		-	41	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Q _g	V _{DS} =50V, I _p =39A, V _{GS} =10V	-	65		nC
Gate-Source Charge	Q _{gs}		-	15.3		nC
Gate-Drain Charge	Q _{gd}		-	9		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V, I _S =78A	-		1.2	V
Diode Forward Current (Note 2)	I _S		-	-	78	A
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = I _S di/dt = 100A/μs (Note3)	-	101		nS
Reverse Recovery Charge	Q _{rr}		-	193		nC

Notes:

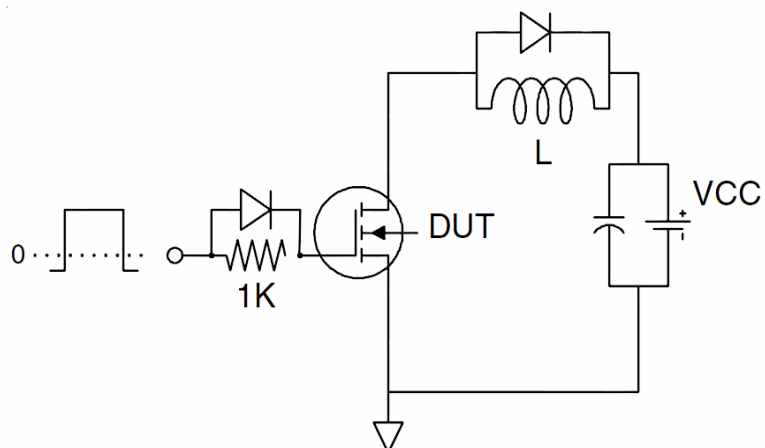
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, L=0.5\text{mH}, R_G=25\Omega$

Test Circuit

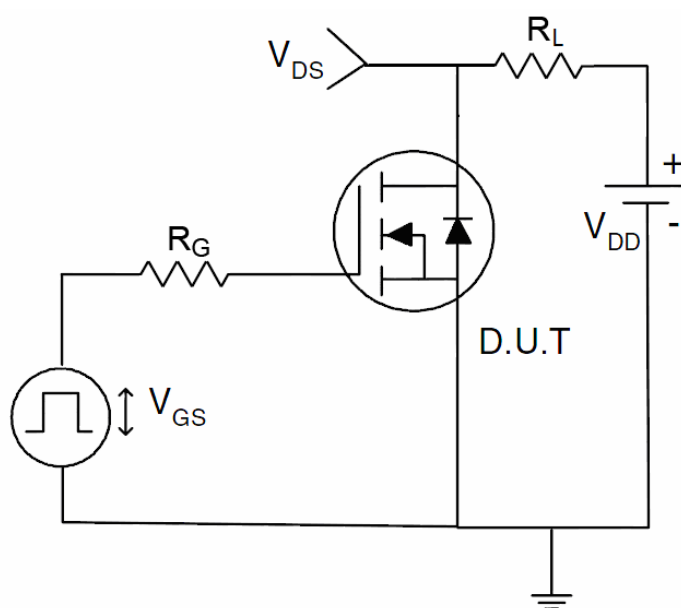
1) E_{AS} test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics

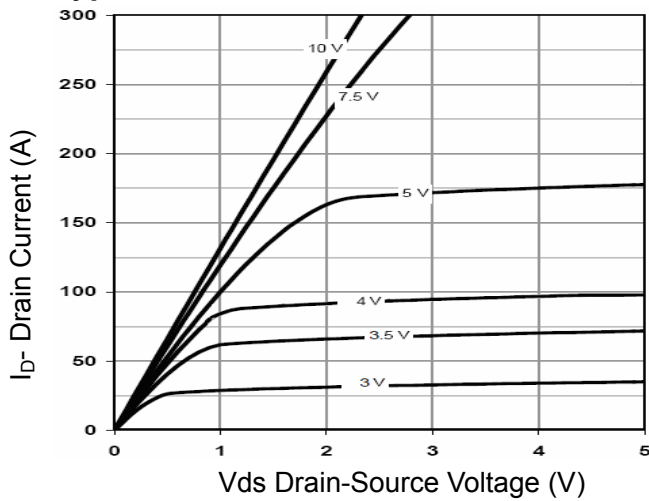


Figure 1 Output Characteristics

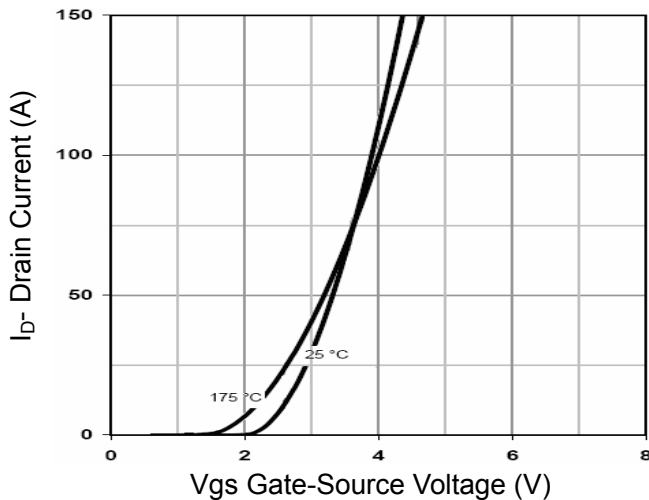


Figure 2 Transfer Characteristics

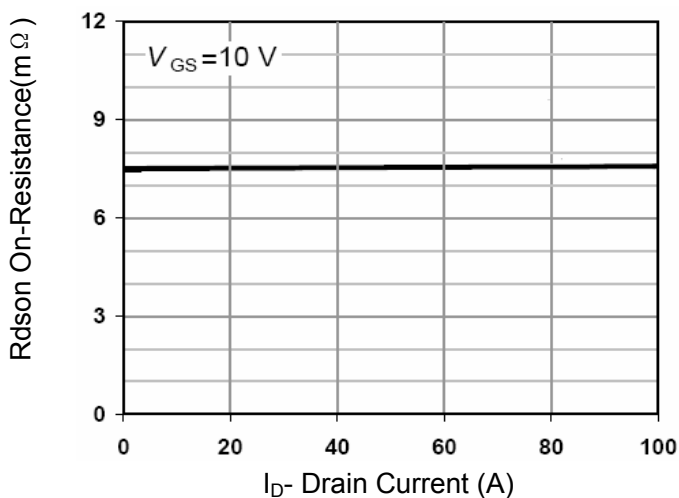


Figure 3 Rdson- Drain Current

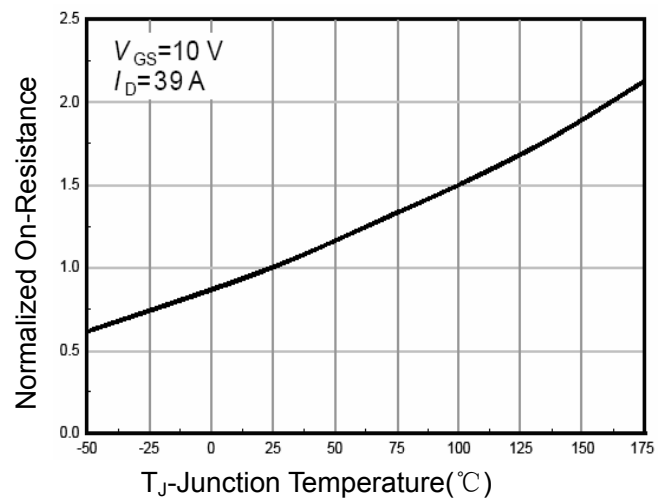


Figure 4 Rdson-Junction Temperature

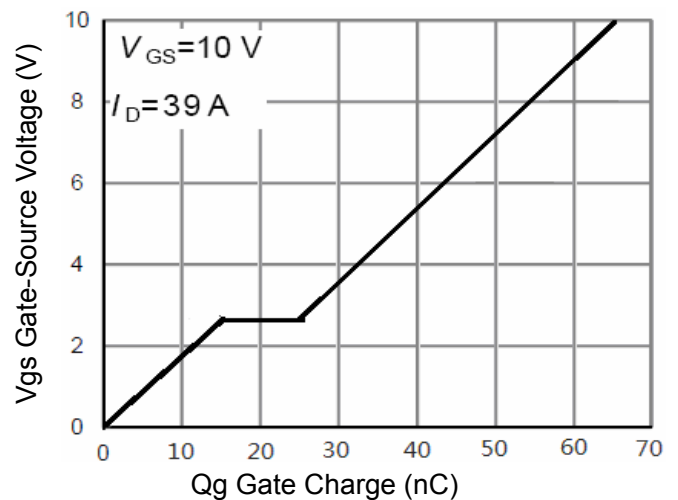


Figure 5 Gate Charge

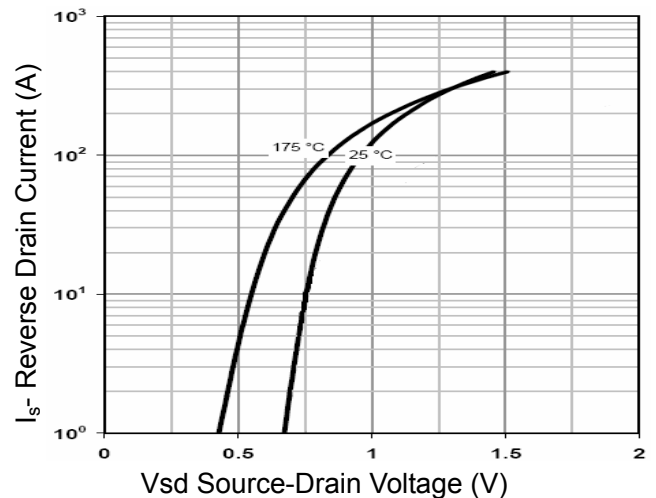


Figure 6 Source- Drain Diode Forward

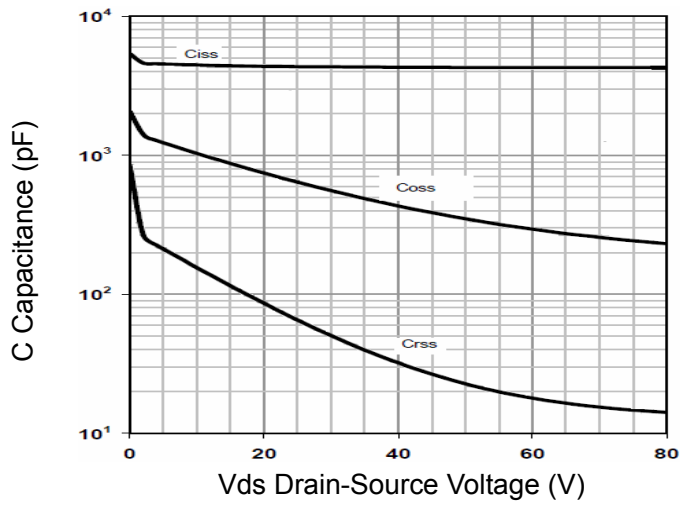


Figure 7 Capacitance vs Vds

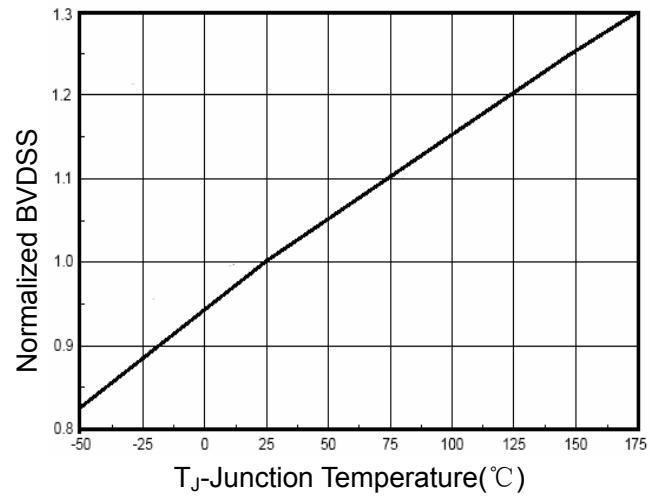


Figure 9 BV_{DSS} vs Junction Temperature

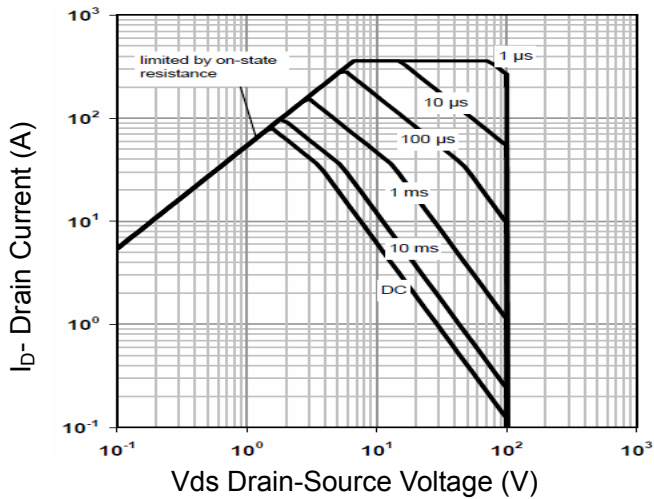


Figure 8 Safe Operation Area

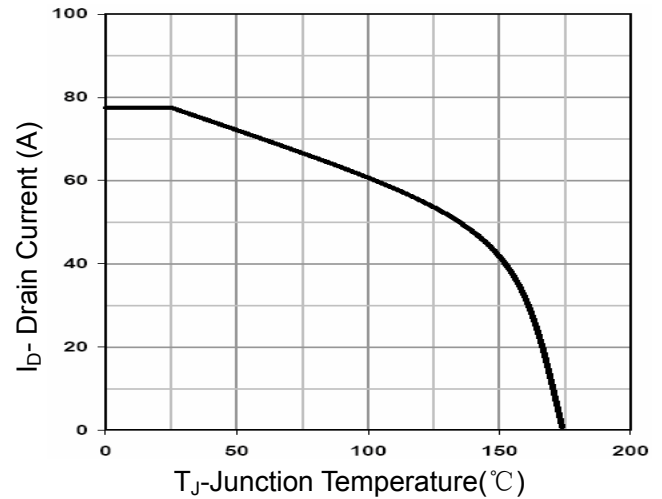


Figure 10 Current De-rating

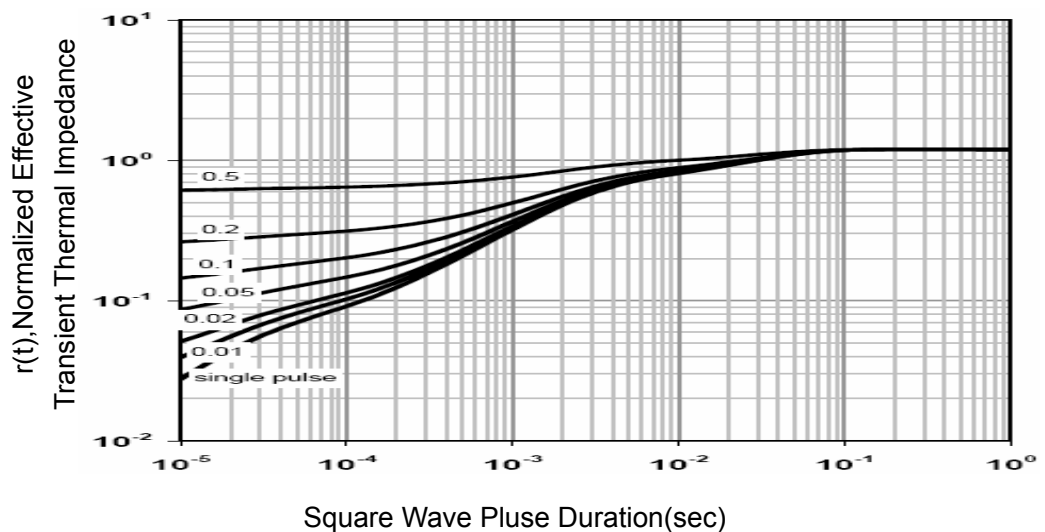
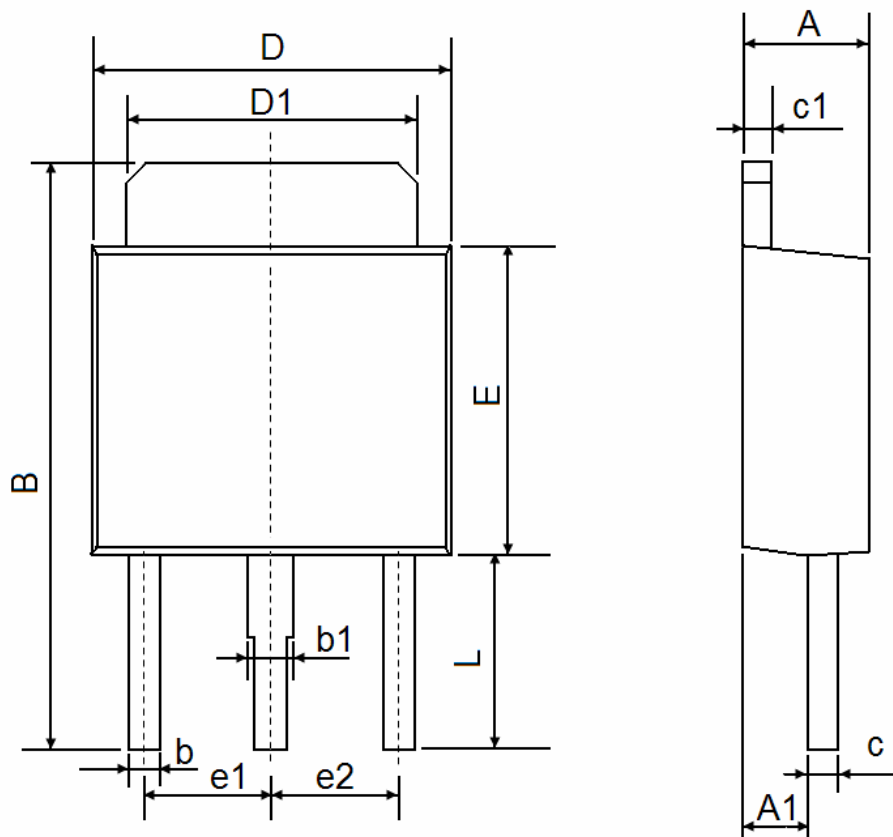


Figure 11 Normalized Maximum Transient Thermal Impedance



TO-251S Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.250	2.350	0.089	0.093
A1	1.150	1.250	0.045	0.049
B	10.200	10.800	0.402	0.425
b	0.550	0.650	0.022	0.026
b1	0.750	0.850	0.030	0.033
c	0.480	0.540	0.019	0.021
c1	0.480	0.540	0.019	0.021
D	6.400	6.600	0.252	0.260
D1	5.250	5.350	0.207	0.211
E	5.400	5.600	0.213	0.220
e1	2.300 TYP		0.091 TYP	
e2	2.300 TYP		0.091 TYP	
L	3.300	3.700	0.130	0.146